

Lorenzo Codecasa

List of Publications by Year in descending order

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169
papers

2,152
citations

279798

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169
docs citations

169
times ranked

662
citing authors

#	ARTICLE	IF	CITATIONS
1	An arnoldi based thermal network reduction method for electro-thermal analysis. IEEE Transactions on Components and Packaging Technologies, 2003, 26, 186-192.	1.3	82
2	Compact modeling of electrical devices for electrothermal analysis. IEEE Transactions on Circuits and Systems Part 1: Regular Papers, 2003, 50, 465-476.	0.1	76
3	Fast novel thermal analysis simulation tool for integrated circuits (FANTASTIC). , 2014, , .		64
4	Circuit-Based Electrothermal Simulation of Power Devices by an Ultrafast Nonlinear MOR Approach. IEEE Transactions on Power Electronics, 2016, 31, 5906-5916.	7.9	63
5	A new set of basis functions for the discrete geometric approach. Journal of Computational Physics, 2010, 229, 7401-7410.	3.8	61
6	A novel approach for generating boundary condition independent compact dynamic thermal networks of packages. IEEE Transactions on Components and Packaging Technologies, 2005, 28, 593-604.	1.3	51
7	Compact Models of Dynamic Thermal Networks with Many Heat Sources. IEEE Transactions on Components and Packaging Technologies, 2007, 30, 653-659.	1.3	47
8	Compact Thermal Networks for Modeling Packages. IEEE Transactions on Components and Packaging Technologies, 2004, 27, 96-103.	1.3	46
9	Symmetric Positive-Definite Constitutive Matrices for Discrete Eddy-Current Problems. IEEE Transactions on Magnetics, 2007, 43, 510-515.	2.1	41
10	Multipoint moment matching reduction from port responses of dynamic thermal networks. IEEE Transactions on Components and Packaging Technologies, 2005, 28, 605-614.	1.3	38
11	Matrix reduction tool for creating boundary condition independent dynamic compact thermal models. , 2015, , .		37
12	Time-Domain Simulation of Nonlinear Circuits Through Implicit Runge–Kutta Methods. IEEE Transactions on Circuits and Systems Part 1: Regular Papers, 2007, 54, 391-400.	0.1	36
13	Analytical Multipoint Moment Matching Reduction of Distributed Thermal Networks. IEEE Transactions on Components and Packaging Technologies, 2004, 27, 87-95.	1.3	33
14	Use of Barycentric Dual Grids for the Solution of Frequency Domain Problems by FIT. IEEE Transactions on Magnetics, 2004, 40, 1414-1419.	2.1	32
15	Compact Dynamic Modeling for Fast Simulation of Nonlinear Heat Conduction in Ultra-Thin Chip Stacking Technology. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2014, 4, 1785-1795.	2.5	32
16	Refoundation of the Cell Method Using Augmented Dual Grids. IEEE Transactions on Magnetics, 2014, 50, 497-500.	2.1	32
17	Canonical forms of one-port Passive Distributed thermal networks. IEEE Transactions on Components and Packaging Technologies, 2005, 28, 5-13.	1.3	31
18	Explicit, Consistent, and Conditionally Stable Extension of FD-TD to Tetrahedral Grids by FIT. IEEE Transactions on Magnetics, 2008, 44, 1258-1261.	2.1	31

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19	Modeling and Simulation of a Hybrid Photovoltaic Module Equipped With a Heat-Recovery System. IEEE Transactions on Industrial Electronics, 2009, 56, 4311-4318.	7.9	31
20	On-Line Junction Temperature Monitoring of Switching Devices with Dynamic Compact Thermal Models Extracted with Model Order Reduction. Energies, 2017, 10, 189.	3.1	31
21	Modeling the thermal response of semiconductor devices through equivalent electrical networks. IEEE Transactions on Circuits and Systems Part 1: Regular Papers, 2002, 49, 1187-1197.	0.1	29
22	Piecewise uniform bases and energetic approach for discrete constitutive matrices in electromagnetic problems. International Journal for Numerical Methods in Engineering, 2006, 65, 548-565.	2.8	29
23	Why matrix reduction is better than objective function based optimization in compact thermal model creation. , 2015, , .		29
24	Base functions and discrete constitutive relations for staggered polyhedral grids. Computer Methods in Applied Mechanics and Engineering, 2009, 198, 1117-1123.	6.6	26
25	Constitutive equations for discrete electromagnetic problems over polyhedral grids. Journal of Computational Physics, 2007, 225, 1894-1918.	3.8	25
26	Delphi-like dynamical compact thermal models using model order reduction. , 2017, , .		24
27	Accurate and efficient analysis of the upward heat flow in InGaP/GaAs HBTs through an automated FEM-based tool and Design of Experiments. International Journal of Numerical Modelling: Electronic Networks, Devices and Fields, 2019, 32, e2530.	1.9	24
28	Thermal networks from heat wave equation. IEEE Transactions on Components and Packaging Technologies, 2005, 28, 14-22.	1.3	23
29	Simulation comparison of InGaP/GaAs HBT thermal performance in wire-bonding and flip-chip technologies. Microelectronics Reliability, 2017, 78, 233-242.	1.7	23
30	Novel approach to compact modeling for nonlinear thermal conduction problems. , 2013, , .		22
31	Analysis of the Influence of Layout and Technology Parameters on the Thermal Impedance of GaAs HBT/BiFET Using a Highly-Efficient Tool. , 2014, , .		22
32	Structure-preserving approach to multi-port dynamic compact models of nonlinear heat conduction. Microelectronics Journal, 2015, 46, 1129-1137.	2.0	22
33	Parametric compact thermal models by moment matching for variable geometry. , 2014, , .		21
34	Thermal feedback blocks for fast and reliable electrothermal circuit simulation of power circuits at module level. , 2016, , .		21
35	Dynamic electro-thermal modeling of solar cells and modules. Solar Energy, 2019, 179, 326-334.	6.1	21
36	Uncertainty Quantification for SAE J2954 Compliant Static Wireless Charge Components. IEEE Access, 2020, 8, 171489-171501.	4.2	21

#	ARTICLE	IF	CITATIONS
37	Compact Modeling of a 3.3 kV SiC MOSFET Power Module for Detailed Circuit-Level Electrothermal Simulations Including Parasitics. <i>Energies</i> , 2021, 14, 4683.	3.1	21
38	Novel MOR approach for extracting dynamic compact thermal models with massive numbers of heat sources. , 2016, , .		20
39	Multi-port dynamic compact thermal models of dual-chip package using model order reduction and metaheuristic optimization. <i>Microelectronics Reliability</i> , 2018, 87, 222-231.	1.7	20
40	Structure preserving approach to parametric dynamic compact thermal models of nonlinear heat conduction. , 2015, , .		19
41	Advanced thermal simulation of SiGe:C HBTs including back-end-of-line. <i>Microelectronics Reliability</i> , 2016, 67, 38-45.	1.7	19
42	Fast Nonlinear Dynamic Compact Thermal Modeling With Multiple Heat Sources in Ultra-Thin Chip Stacking Technology. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2017, 7, 58-69.	2.5	18
43	Novel Approach to the Extraction of Delphi-like Boundary-Condition-Independent Compact Thermal Models of Planar Transformer Devices. , 2018, , .		18
44	Circuit-Based Electrothermal Simulation of Multicellular SiC Power MOSFETs Using FANTASTIC. <i>Energies</i> , 2020, 13, 4563.	3.1	17
45	Compact thermal networks for conjugate heat transfer by moment matching. , 2008, , .		16
46	Multi-port dynamic compact thermal models of nonlinear heat conduction. , 2014, , .		16
47	Stochastic Finite Integration Technique Formulation for Electrokinetics. <i>IEEE Transactions on Magnetics</i> , 2014, 50, 573-576.	2.1	16
48	Compact electro-thermal models of interconnects. <i>Microelectronics Journal</i> , 2014, 45, 1777-1785.	2.0	15
49	Calibration of detailed thermal models by parametric dynamic compact thermal models. , 2016, , .		15
50	Modeling Thermal Coupling in Bipolar Power Amplifiers toward Dynamic Electrothermal Simulation. , 2018, , .		15
51	Analysis of Electrothermal Effects in Devices and Arrays in InGaP/GaAs HBT Technology. <i>Electronics (Switzerland)</i> , 2021, 10, 757.	3.1	15
52	Structure Function Representation of Multidirectional Heat-Flows. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2007, 30, 643-652.	1.3	14
53	Stochastic thermal modeling by polynomial chaos expansion. , 2013, , .		14
54	Compact electro-thermal models of interconnects. , 2013, , .		14

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55	Nonlinear dynamic compact thermal models by structure-preserving projection. <i>Microelectronics Journal</i> , 2014, 45, 1764-1769.	2.0	14
56	Compact thermal models for stochastic thermal analysis. <i>Microelectronics Journal</i> , 2014, 45, 1770-1776.	2.0	14
57	Novel approach for the extraction of nonlinear compact thermal models. , 2017, , .		14
58	Versatile MOR-based boundary condition independent compact thermal models with multiple heat sources. <i>Microelectronics Reliability</i> , 2018, 87, 194-205.	1.7	14
59	Multivariate moment matching for generating boundary condition independent compact dynamic thermal networks of packages. , 0, , .		13
60	An Efficient Simulation Methodology to Quantify the Impact of Parameter Fluctuations on the Electrothermal Behavior of Multichip SiC Power Modules. <i>Materials Science Forum</i> , 0, 963, 855-858.	0.3	13
61	Thermal networks for electro-thermal analysis of power devices. <i>Microelectronics Journal</i> , 2001, 32, 817-822.	2.0	12
62	Event-Driven Time-Domain Simulation of Closed-Loop Switched Circuits. <i>IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems</i> , 2006, 25, 2413-2426.	2.7	12
63	Connecting MOR-based boundary condition independent compact thermal models. , 2017, , .		12
64	Experimental Characterization of MOR-based and Delphi-like BCI DCTMs. , 2018, , .		12
65	Boundary condition independent compact models of dynamic thermal networks with many heat sources. , 0, , .		11
66	Novel Feedback Theory of Electric Circuitsâ€™ Part I: Cut-Based Decomposition. <i>IEEE Transactions on Circuits and Systems I: Regular Papers</i> , 2012, 59, 1491-1504.	5.4	11
67	Novel partition-based approach to dynamic compact thermal modeling. , 2016, , .		11
68	A 3-D Hybrid Cell Method for Induction Heating Problems. <i>IEEE Transactions on Magnetics</i> , 2017, 53, 1-4.	2.1	11
69	Influence of layout and technology parameters on the thermal behavior of InGaP/GaAs HBTs. , 2017, , .		11
70	Thermal Resistance Advanced Calculator (TRAC). , 2018, , .		11
71	A <i>a priori</i> Error Bound for Moment Matching Approximants of Thermal Models. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2019, 9, 2383-2392.	2.5	11
72	Physical interpretation and numerical approximation of structure functions of components and packages. , 0, , .		10

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73	On the performance of piezoelectric harvesters loaded by finite width impulses. <i>Mechanical Systems and Signal Processing</i> , 2018, 100, 28-42.	8.0	10
74	A 3-D Hybrid Cell Boundary Element Method for Time-Harmonic Eddy Current Problems on Multiply Connected Domains. <i>IEEE Transactions on Magnetics</i> , 2019, 55, 1-11.	2.1	10
75	Exploiting Port Responses for Wideband Analysis of Multimode Lossless Devices. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2020, 68, 555-563.	4.6	10
76	Discrete Geometric Formulation of Admittance Boundary Conditions for Frequency Domain Problems Over Tetrahedral Dual Grids. <i>IEEE Transactions on Antennas and Propagation</i> , 2012, 60, 3998-4002.	5.1	9
77	Fast MOR-Based Approach to Uncertainty Quantification in Transcranial Magnetic Stimulation. <i>IEEE Transactions on Magnetics</i> , 2016, 52, 1-4.	2.1	9
78	Fast Solution of Induction Heating Problems by Structure-Preserving Nonlinear Model Order Reduction. <i>IEEE Transactions on Magnetics</i> , 2016, 52, 1-4.	2.1	9
79	Partition-based approach to parametric dynamic compact thermal modeling. <i>Microelectronics Reliability</i> , 2017, 79, 361-370.	1.7	9
80	TRAC: A Thermal Resistance Advanced Calculator for Electronic Packages. <i>Energies</i> , 2019, 12, 1050.	3.1	9
81	Model-Order Reduction Procedure for Fast Dynamic Electrothermal Simulation of Power Converters. <i>Lecture Notes in Electrical Engineering</i> , 2019, , 81-87.	0.4	9
82	Indirect Coupling of the Cell Method and BEM for Solving 3-D Unbounded Magnetostatic Problems. <i>IEEE Transactions on Magnetics</i> , 2016, 52, 1-4.	2.1	8
83	3-D thermal models calibration by parametric dynamic compact thermal models. <i>Microelectronics Reliability</i> , 2017, 79, 371-379.	1.7	8
84	Novel FDTD Technique Over Tetrahedral Grids for Conductive Media. <i>IEEE Transactions on Antennas and Propagation</i> , 2018, 66, 5387-5396.	5.1	8
85	A geometric integral formulation for eddy currents. <i>International Journal for Numerical Methods in Engineering</i> , 2010, 82, 1720-1736.	2.8	7
86	Plane Wave Excitation for Frequency Domain Electromagnetic Problems by Means of Impedance Boundary Condition. <i>IEEE Transactions on Magnetics</i> , 2015, 51, 1-4.	2.1	7
87	Stochastic Finite Integration Technique for Eddy-Current Problems. <i>IEEE Transactions on Magnetics</i> , 2015, 51, 1-4.	2.1	7
88	Electro-thermal resonance in MOSFET devices. <i>Electronics Letters</i> , 2001, 37, 57.	1.0	6
89	Accurate electro-thermal model of avalanching junctions subject to ESD currents. <i>Electronics Letters</i> , 2003, 39, 932.	1.0	6
90	Evaluating the effects of temperature gradients and currents nonuniformity in on-chip interconnects. <i>Microelectronics Journal</i> , 2009, 40, 1154-1159.	2.0	6

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91	A Novel Inversion Technique for Imaging Thrombus Volume in Microchannels Fusing Optical and Impedance Data. IEEE Transactions on Magnetics, 2014, 50, 1021-1024.	2.1	6
92	Advanced thermal resistance simulation of SiGe HBTs including backend cooling effect. , 2015, , .		6
93	Dynamic electrothermal simulation of photovoltaic plants. , 2015, , .		6
94	Harmonic Balance Based on Two-Step Galerkin Method. IEEE Transactions on Circuits and Systems I: Regular Papers, 2016, 63, 1476-1486.	5.4	6
95	Combined SPICE-FEM analysis of electrothermal effects in InGaP/GaAs HBT devices and arrays for handset applications. , 2018, , .		6
96	GPU Accelerated Time-Domain Discrete Geometric Approach Method for Maxwell's Equations on Tetrahedral Grids. IEEE Transactions on Magnetics, 2018, 54, 1-4.	2.1	6
97	Shooting by a Two-Step Galerkin Method. IEEE Transactions on Circuits and Systems I: Regular Papers, 2019, 66, 383-390.	5.4	6
98	A Novel "FIT" Approach for Solving Eddy Current Problems in Multiply Connected Regions. IEEE Access, 2020, 8, 170659-170671.	4.2	6
99	Accurate and Efficient Algorithm for Computing Structure Functions From the Spatial Distribution of Thermal Properties in Electronic Devices. IEEE Transactions on Electron Devices, 2021, 68, 5386-5393.	3.0	6
100	Galerkin's Projection Framework for BCI CTMs"Part I: Extended FANTASTIC Approach. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 1792-1803.	2.5	6
101	Electro-thermal chaotic oscillations of paralleled bipolar transistors. Microelectronics Journal, 2004, 35, 859-868.	2.0	5
102	Parametric Compact Models by Directional Moment Matching. , 0, , .		5
103	MOR-Based Approach to Uncertainty Quantification in Electrokinetics With Correlated Random Material Parameters. IEEE Transactions on Magnetics, 2017, 53, 1-4.	2.1	5
104	Thermal Resistance and Impedance Calculator (TRIC). , 2019, , .		5
105	TRIC: A Thermal Resistance and Impedance Calculator for Electronic Packages. Energies, 2020, 13, 2252.	3.1	5
106	Coupling the Cell Method with the Boundary Element Method in Static and Quasi-Static Electromagnetic Problems. Mathematics, 2021, 9, 1426.	2.2	5
107	Triangulation method for structure functions of multi-directional heat-flows. , 2008, , .		4
108	A FIT Formulation of Bianisotropic Materials Over Polyhedral Grids. IEEE Transactions on Magnetics, 2014, 50, 349-352.	2.1	4

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109	Novel Approach to Model Order Reduction for Nonlinear Eddy-Current Problems. IEEE Transactions on Magnetics, 2015, 51, 1-4.	2.1	4
110	2-D Stabilized FIT Formulation for Eddy-Current Problems in Moving Conductors. IEEE Transactions on Magnetics, 2015, 51, 1-4.	2.1	4
111	Numerical analysis of the thermal behavior sensitivity to technology parameters and operating conditions in InGaP/GaAs HBTs. , 2017, , .		4
112	Fast Uncertainty Quantification in Low Frequency Electromagnetic Problems by an Integral Equation Method Based on Hierarchical Matrix Compression. IEEE Access, 2019, 7, 163919-163932.	4.2	4
113	Stochastic PEEC Method Based on Polynomial Chaos Expansion. IEEE Transactions on Magnetics, 2019, 55, 1-4.	2.1	4
114	The Time-Domain Cell Method Is a Coupling of Two Explicit Discontinuous Galerkin Schemes With Continuous Fluxes. IEEE Transactions on Magnetics, 2020, 56, 1-4.	2.1	4
115	Closed-Form expression of frequency pulling in unlocked-driven nonlinear oscillators. , 2007, , .		3
116	Multi-physics analysis of a photovoltaic panel with a heat recovery system. , 2008, , .		3
117	Subgridding to Solving Magnetostatics Within Discrete Geometric Approach. IEEE Transactions on Magnetics, 2009, 45, 1024-1027.	2.1	3
118	Constitutive Relations for Discrete Geometric Approach Over Hexahedral Grids. IEEE Transactions on Magnetics, 2010, 46, 3077-3080.	2.1	3
119	A Perturbation Method for the T - Ω Geometric Eddy-Current Formulation. IEEE Transactions on Magnetics, 2010, 46, 3045-3048.	2.1	3
120	Time-Domain Geometric Eddy-Current TT Formulation for Hexahedral Grids. IEEE Transactions on Magnetics, 2010, 46, 3301-3304.	2.1	3
121	Novel Feedback Theory of Electric Circuitsâ€™ Part II: Loop Invariants. IEEE Transactions on Circuits and Systems I: Regular Papers, 2012, 59, 1505-1518.	5.4	3
122	Reduction of harmonic balance equations through Galerkin's method. , 2015, , .		3
123	Geometrically defined basis functions for polyhedral elements with applications to computational electromagnetics. ESAIM: Mathematical Modelling and Numerical Analysis, 2016, 50, 677-698.	1.9	3
124	Stochastic finite integration technique for magnetostatic problems. International Journal of Numerical Modelling: Electronic Networks, Devices and Fields, 2017, 30, e2209.	1.9	3
125	An arbitrary-order Cell Method with block-diagonal mass-matrices for the time-dependent 2D Maxwell equations. Journal of Computational Physics, 2021, 433, 110184.	3.8	3
126	TONIC: TOOl for Nonlinear BCI CTMs of Integrated Circuits. , 2021, , .		3

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127	Multilevel Monte Carlo FDTD Method for Uncertainty Quantification. IEEE Antennas and Wireless Propagation Letters, 2022, 21, 2030-2034.	4.0	3
128	The discrete geometric approach for wave propagation problems. , 2009, , .		2
129	Generalized spectral decomposition approach to a stochastic finite integration technique electrokinetic formulation. , 2014, , .		2
130	Corona Discharge Simulation of Multiconductor Electrostatic Precipitators. IEEE Transactions on Magnetics, 2016, 52, 1-4.	2.1	2
131	Complementary Discrete Geometric \mathcal{H}^1 Field Formulation for Wave Propagation Problems. IEEE Transactions on Magnetics, 2016, 52, 1-4.	2.1	2
132	Excitation by Scattering/Total Field Decomposition and Uniaxial PML in the Geometric Formulation. IEEE Transactions on Magnetics, 2016, 52, 1-4.	2.1	2
133	Nonlinear model order reduction for the fast solution of induction heating problems in time-domain. COMPEL - the International Journal for Computation and Mathematics in Electrical and Electronic Engineering, 2017, 36, 469-475.	0.9	2
134	Uncertainty quantification in transcranial magnetic stimulation with correlation between tissue conductivities. , 2017, , .		2
135	Wideband analysis of lossless multimode waveguide junctions. , 2017, , .		2
136	E-Plane Metal-Insert Filters with Pseudo-Elliptic Response. , 2018, , .		2
137	Three-Steps Approach to Uncertainty Quantification for Electronic Components and Packages. , 2019, , .		2
138	Algorithm for Establishing the Dependence of Structure Functions on Spatial Distributions of Thermal Properties. , 2019, , .		2
139	Enforcing Lumped Parameter Excitations in Edge-Element Formulations by Using a Fast Iterative Approach. IEEE Transactions on Magnetics, 2020, 56, 1-4.	2.1	2
140	Exact conic section arc elements in 2D and 2.5D FEM using a coordinate transformation. IET Microwaves, Antennas and Propagation, 2021, 15, 1108-1116.	1.4	2
141	Electrothermal Modeling, Simulation, and Electromagnetic Characterization of a 3.3 kV SiC MOSFET Power Module. , 2021, , .		2
142	Domain Decomposition With Non-Conforming Polyhedral Grids. IEEE Access, 2021, 9, 1465-1481.	4.2	2
143	Thermal Modeling of BGA Package Families Using the Thermal Resistance and Impedance Calculator (TRIC). , 2020, , .		2
144	Towards the Extension of TRIC for Thermo-Mechanical Analysis. , 2021, , .		2

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145	A Hybrid $\hat{\mathcal{H}}$ Cell Method for Solving Eddy-Current Problems in 3D Multiply-Connected Domains. IEEE Access, 2021, 9, 158247-158260.	4.2	2
146	Altering MOR-based BCI CTMs into Delphi-like BCI CTMs. , 2020, , .		2
147	Solution of Boundary-Value Problems in Frequency Domain by a Dual Grid Second-Order FD Technique. , 2000, , .		1
148	Steady-state analysis of strongly nonlinear Oscillators By Means of Runge-Kutta Methods. , 2008, , .		1
149	Complementary Energy Bounds in FIT for Magnetostatics. IEEE Transactions on Magnetics, 2015, 51, 1-4.	2.1	1
150	Modeling of Anechoic Chambers With Equivalent Materials and Equivalent Sources. IEEE Transactions on Electromagnetic Compatibility, 2016, 58, 956-963.	2.2	1
151	A Geometric Frequency-Domain Wave Propagation Formulation for Fast Convergence of Iterative Solvers. IEEE Transactions on Magnetics, 2017, 53, 1-4.	2.1	1
152	Uncertainty quantification in linear magnetostatic problems with correlated random reluctivities. International Journal of Applied Electromagnetics and Mechanics, 2017, 55, 177-183.	0.6	1
153	Practical Thermal Modeling of Planar Magnetic Component devices. , 2019, , .		1
154	A face-smoothed cell method for static and dynamic piezoelectric coupled problems on polyhedral meshes. Journal of Computational Physics, 2019, 386, 84-109.	3.8	1
155	MOR-Based Uncertainty Quantification in Transcranial Magnetic Stimulation. Modeling, Simulation and Applications, 2017, , 421-437.	1.3	1
156	An Approach to the Cell-Level Diagnosis of Malfunctioning Events in PV Panels from Aerial Thermal Maps. Lecture Notes in Electrical Engineering, 2020, , 89-102.	0.4	1
157	Full Wave Derivation of Equivalent Circuit for Waveguide Dielectric Resonator Filter. , 2001, , .		0
158	Semi-implicit integration method for the time-domain simulation of thermal responses. , 2008, , .		0
159	A non-destructive testing application solved with $\hat{\mathcal{H}}$ geometric eddy-current formulation. COMPEL - the International Journal for Computation and Mathematics in Electrical and Electronic Engineering, 2010, 29, 1606-1615.	0.9	0
160	A geometric frequency-domain wave propagation formulation for fast convergence of iterative solvers. , 2016, , .		0
161	A novel finite integration technique model for static and dynamic piezoelectric coupled problems. , 2016, , .		0
162	A 3D hybrid cell method for induction heating problems. , 2016, , .		0

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163	Real-time temperature cycling estimation of IGBT power modules with power in-line measurements and compact thermal modeling. , 2016, , .		0
164	MOR-based approach to uncertainty quantification in electrokinetics with correlated random material parameters. , 2016, , .		0
165	A comparative performance analysis of time-domain formulations for wave propagation problems. , 2016, , .		0
166	Model order reduction approach to uncertainty quantification in eddy current problems. , 2017, , .		0
167	Compact Electro-Thermal Models for Integrated Systems. , 2021, , .		0
168	Trefftz co-chain calculus. Zeitschrift Fur Angewandte Mathematik Und Physik, 2022, 73, 43.	1.4	0
169	Defect Detection in Double-Sided Cooled Power Modules by Structure Functions. , 2022, , .		0